

DV1210S ■ DV1210W ■ DV1210Z

N-Channel Enhancement - Mode RF Power FETs

**175 MHz 10 W
10-20 V 10 dB**

**Other Devices in Series:
DV1202, DV1205, DV1220, DV1230, DV1240, DV1260**



Siliconix

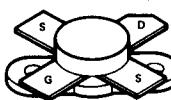
April 1982

Island Labs

FEATURES

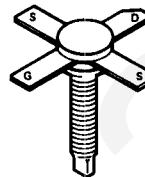
- Infinite VSWR
- No Thermal Runaway
- Broadband Capability
- Class A, B, C, D, E
- Low Noise Figure
- High Dynamic Range
- Simple Bias Circuitry

Package Type S



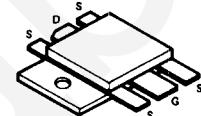
.380 SOE Flange

Package Type Z



.280 SOE Stud

Package Type W



C-220

See page 5-62 for Package Dimensions

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

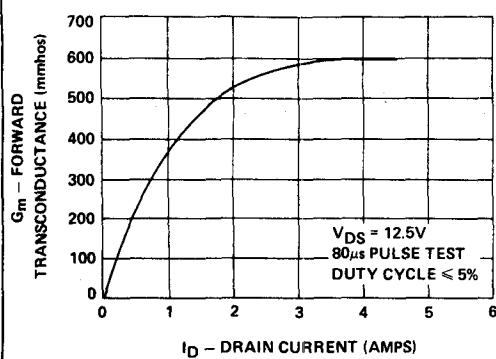
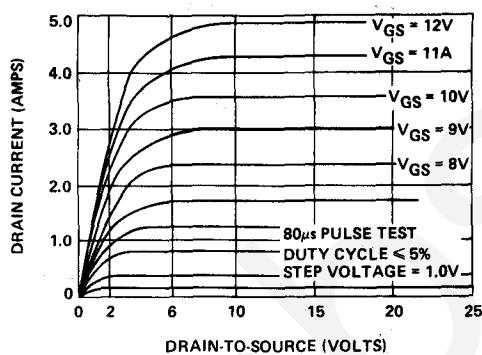
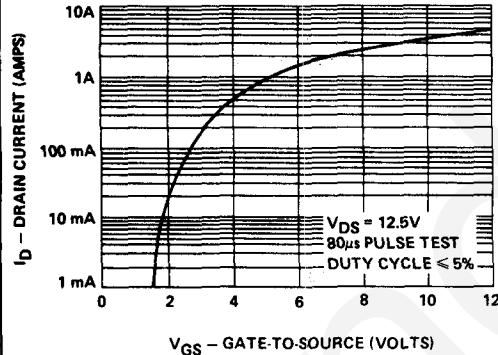
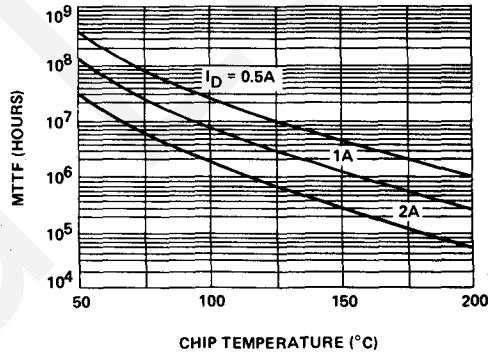
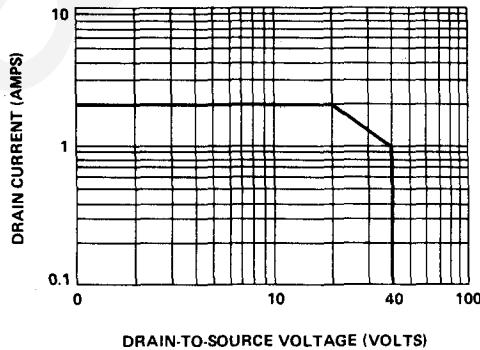
Gate-Source Voltage	30V	Total Device Dissipation	40W
Drain-Source Voltage	45V	Thermal Resistance, Junction to Case	4.4°C/W
Drain-Gate Voltage	45V	Junction Temperature	200°C
Drain Current (DC)	2A	Storage Temperature	-65°C to 150°C

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Characteristics	Min	Typ	Max	Unit	Test Conditions
BV_{DSS}	Drain-Source Breakdown Voltage	45			V	$V_{\text{GS}} = 0\text{V}$, $I_D = 5\text{ mA}$
I_{DSS}	Drain-Source Leakage Current			0.5	mA	$V_{\text{GS}} = 0\text{V}$, $V_{\text{DS}} = 15\text{V}$
I_{GSS}	Gate-Source Leakage Current			100	nA	$V_{\text{GS}} = 30\text{V}$, $V_{\text{DS}} = 0\text{V}$
g_m	D.C. Forward Transconductance	0.2	0.4		Mho	$V_{\text{DS}} = 10\text{V}$, $I_D = 1\text{A}$, $\Delta V_{\text{GS}} = 1.0\text{V}$
$I_{\text{D(on)}}$	On-State Drain Current		3.5		A	$V_{\text{DS}} = 12\text{V}$, $V_{\text{GS}} = 10\text{V}$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	2		6	V	$V_{\text{GS}} = V_{\text{DS}}$, $I_D = 100\text{ mA}$
C_{iss}	Common-Source Input Capacitance			50	pF	$V_{\text{GS}} = 0\text{V}$, $V_{\text{DS}} = 12.5\text{V}$, $f = 1.0\text{ MHz}$
C_{oss}	Common-Source Output Capacitance			60	pF	$V_{\text{GS}} = 0\text{V}$, $V_{\text{DS}} = 12.5\text{V}$, $f = 1.0\text{ MHz}$
C_{rss}	Reverse Transfer Capacitance			10	pF	$V_{\text{GS}} = 0\text{V}$, $V_{\text{DS}} = 12.5\text{V}$, $f = 1.0\text{ MHz}$
G_{ps}	Common-Source Power Gain	10			dB	$V_{\text{DD}} = 12.5\text{V}$, $P_o = 10\text{W}$, $f = 175\text{ MHz}$, $I_{\text{DQ}} = 1.0\text{ A}$
η	Drain Efficiency		65		%	$V_{\text{DD}} = 12.5\text{V}$, $P_o = 10\text{W}$, $f = 175\text{ MHz}$, $I_{\text{DQ}} = 1.0\text{ A}$
V_{SWR}	Load Mismatch Tolerance	30:1				$V_{\text{DD}} = 12.5\text{V}$, $P_o = 10\text{W}$, $f = 175\text{ MHz}$, $I_{\text{DQ}} = 1.0\text{ A}$

Note 1: Pulse Test — 80μs to 300μs, 1% duty cycle

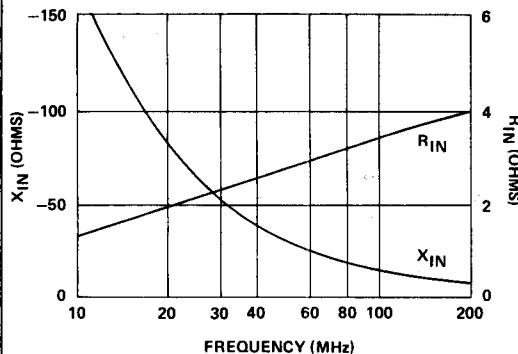
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TYPICAL PERFORMANCE CURVES ($T_C = 25^\circ\text{C}$ unless otherwise noted)**Typical Transconductance vs Drain Current****Typical Output Characteristics****Typical Transfer Characteristics****MTTF vs Chip Temperature****DC Safe Operating Region**

TYPICAL PERFORMANCE CURVES-CONTINUED

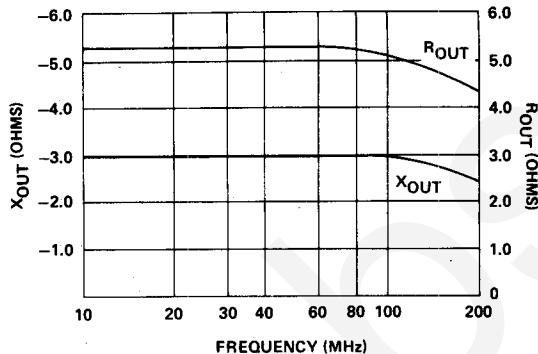
DV1210S

Series Input Impedance vs Frequency

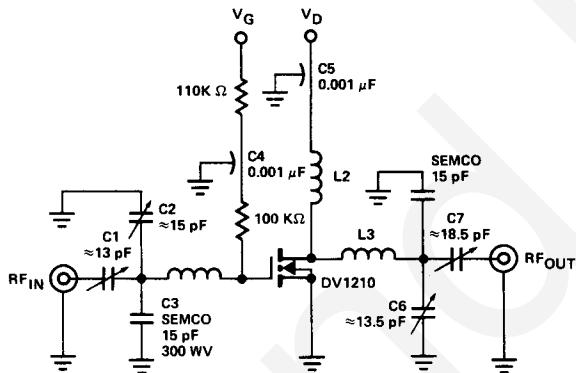


DV1210S

Series Output Impedance vs Frequency



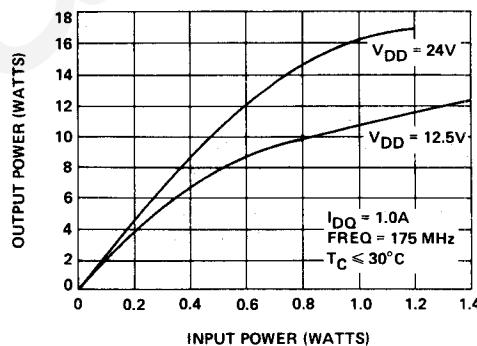
175 MHz TEST FIXTURE



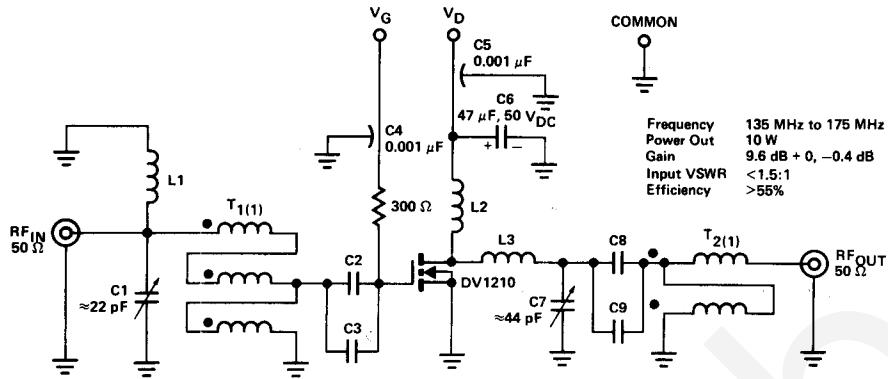
PARTS LIST

C1, C2, C5, C6, Arco #462, 5 to 80 pF
L1, 2 1/2" length of #AWG 12, 1/2 turn on 1/3" diameter
L2, 8 turns #AWG 22 on 1/4" diameter, close wound
L3, 1 5/8" length of #AWG 12, 1/2 turn on 1/3" diameter

Typical Output Power vs Input Power



APPLICATIONS



PARTS LIST

C1, Arco #462 trimmer capacitor, 5 to 80 pF
 C7, Arco #463 trimmer capacitor, 9 to 180 pF
 L1, 2 turns, #AWG 22 on 1/4" diameter close wound
 L2, 7 turns, #AWG 22 on 1/4" diameter close wound
 L3, 1/2" #AWG 18 buss, 1/2-turn on 1/4" diameter

C2, C3, C8, C9, 0.01 μ F chip capacitors,
 Johanson P/N 201 L64 N 103 MA
 T1, One turn #22 enamel wire trifilar twisted with 13 crests
 per inch on one Stackpole balun core #57-0973
 T2, One turn 25Ω coax wound on two balun cores placed
 end on end. Stackpole balun cores #57-0973
 (1) — Dot indicates winding starts

CAUTION: Beryllium Oxide — The top cap of this device is alumina which is harmless. However the ceramic portion between the leads and the metal flange is Beryllium Oxide, the dust of which is toxic. Care must therefore be taken during handling and mounting the device to prevent any damage to this area.

Steps must be taken to ensure that all those who may handle, use, or dispose of this device are aware of its nature and of these necessary safety precautions. In particular the transistor should never be thrown out with general industrial or domestic waste.